

REGULATORY COMPLIANCE











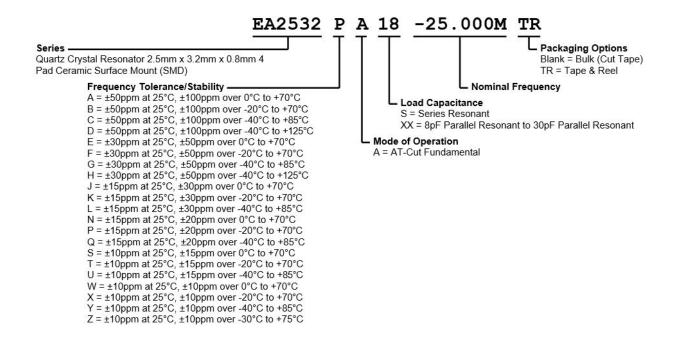
ITEM DESCRIPTION

Quartz Crystal Resonator 2.5mm x 3.2mm x 0.8mm 4 Pad Ceramic Surface Mount (SMD)

| ELECTRICAL SPECIFICATIONS | | |
|-------------------------------|---|--|
| Nominal Frequency | 10MHz to 54MHz | |
| Frequency Tolerance/Stability | ±50ppm at 25°C, ±100ppm over 0°C to +70°C ±50ppm at 25°C, ±100ppm over -20°C to +70°C ±50ppm at 25°C, ±100ppm over -40°C to +85°C ±50ppm at 25°C, ±100ppm over -40°C to +125°C ±30ppm at 25°C, ±50ppm over 0°C to +70°C ±30ppm at 25°C, ±50ppm over -20°C to +70°C ±30ppm at 25°C, ±50ppm over -40°C to +85°C ±30ppm at 25°C, ±50ppm over -40°C to +85°C ±30ppm at 25°C, ±50ppm over -40°C to +125°C ±15ppm at 25°C, ±30ppm over 0°C to +70°C ±15ppm at 25°C, ±30ppm over -20°C to +70°C ±15ppm at 25°C, ±30ppm over -40°C to +85°C ±15ppm at 25°C, ±20ppm over -40°C to +70°C ±15ppm at 25°C, ±20ppm over -20°C to +70°C ±15ppm at 25°C, ±20ppm over -20°C to +70°C ±15ppm at 25°C, ±15ppm over 0°C to +85°C ±10ppm at 25°C, ±15ppm over 0°C to +70°C ±10ppm at 25°C, ±15ppm over -40°C to +85°C ±10ppm at 25°C, ±15ppm over -40°C to +85°C ±10ppm at 25°C, ±15ppm over -20°C to +70°C ±10ppm at 25°C, ±15ppm over -20°C to +70°C ±10ppm at 25°C, ±15ppm over -20°C to +70°C ±10ppm at 25°C, ±15ppm over -40°C to +85°C (Only available over Nominal Frequency range of 12MHz to 54MHz) ±10ppm at 25°C, ±10ppm over -20°C to +70°C ±10ppm at 25°C, ±10ppm over -20°C to +85°C (Only available over Nominal Frequency range of 20.000001MHz to 54MHz) | |
| Aging at 25°C | ±3ppm/year Maximum | |
| Load Capacitance | Series Resonant, 8pF Parallel Resonant to 30pF Parallel Resonant | |
| Shunt Capacitance | 5pF Maximum | |
| Equivalent Series Resistance | 250 Ohms Maximum over Nominal Frequency of 10MHz to 11.999999MHz 150 Ohms Maximum over Nominal Frequency of 12MHz to 13.999999MHz 100 Ohms Maximum over Nominal Frequency of 14MHz to 15.999999MHz 80 Ohms Maximum over Nominal Frequency of 16MHz to 19.999999MHz 60 Ohms Maximum over Nominal Frequency of 20MHz to 29.999999MHz 50 Ohms Maximum over Nominal Frequency of 30MHz to 53.999999MHz 35 Ohms Maximum over Nominal Frequency of 54MHz to 54MHz | |
| Mode of Operation | AT-Cut Fundamental | |
| Drive Level | 100μWatts Maximum | |
| Crystal Cut | AT-Cut | |
| Spurious Response | Measured from Fo to Fo +5000ppm -3dB Minimum | |
| Storage Temperature Range | -40°C to +150°C | |
| Insulation Resistance | Measured at 100Vdc 500 Megaohms Minimum | |

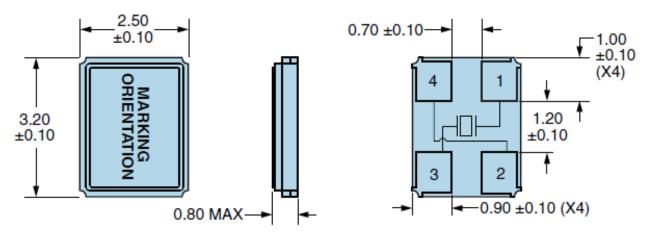


PART NUMBERING GUIDE





MECHANICAL DIMENSIONS

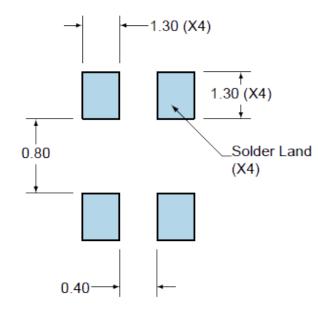


Note: Chamfer not shown.

Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0μm) over Nickel (1.27 to 8.89μm).

SUGGESTED SOLDER PAD LAYOUT



| PIN | CONNECTION |
|-----|--------------|
| 1 | Crystal |
| 2 | Cover/Ground |
| 3 | Crystal |
| 4 | Cover/Ground |

All Tolerances are ±0.1

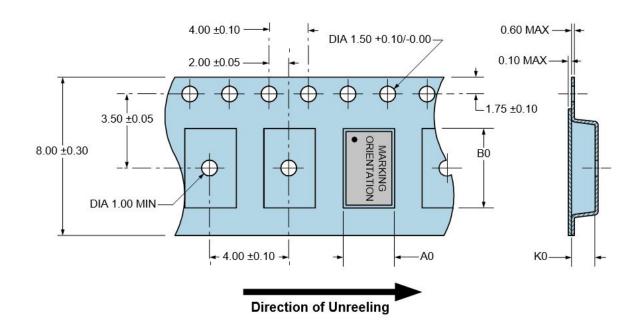
All Dimensions in Millimeters

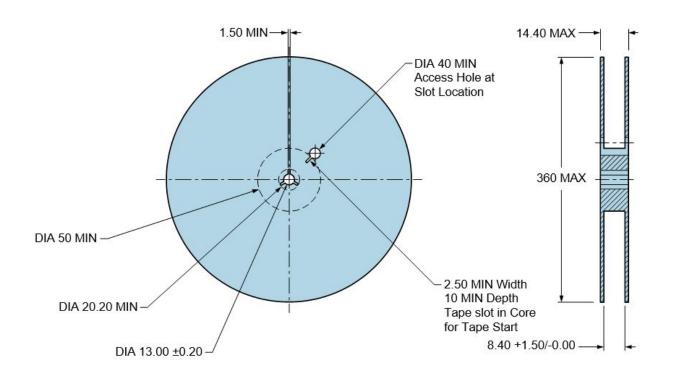


TAPE & REEL DIMENSIONS

Quantity per Reel: 1,000 Units

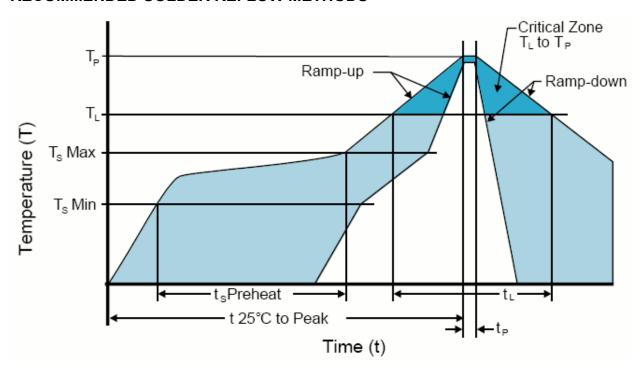
All Dimensions in Millimeters
Compliant to EIA-481







RECOMMENDED SOLDER REFLOW METHODS



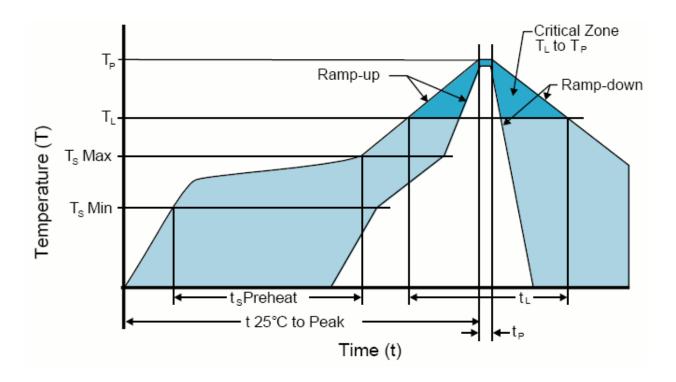
| HIGH TEMPERATURE INFRARED/CONVECTION | | |
|---|---|--|
| T _s MAX to T _L (Ramp-up Rate) | 3°C/Second Maximum | |
| Preheat | | |
| - Temperature Minimum (T _s MIN) | 150°C | |
| - Temperature Typical (T _s TYP) | 175°C | |
| - Temperature Maximum(T _s MAX) | 200°C | |
| - Time (t _s MIN) | 60 - 180 Seconds | |
| Ramp-up Rate (T _L to T _P) | 3°C/Second Maximum | |
| Time Maintained Above: | | |
| - Temperature (T _L) | 217°C | |
| - Time (t _L) | 60 - 150 Seconds | |
| Peak Temperature (T _P) | 260°C Maximum for 10 Seconds Maximum | |
| Target Peak Temperature(T _P Target) | 250°C +0/-5°C | |
| Time within 5°C of actual peak (tp) | 20 - 40 Seconds | |
| Ramp-down Rate | 6°C/Second Maximum | |
| Time 25°C to Peak Temperature (t) | 8 Minutes Maximum | |
| Moisture Sensitivity Level | Level 1 | |
| Additional Notes | Temperatures shown are applied to body of device. | |

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHODS



| LOW TEMPERATURE INFRARED/CONVECTION | | |
|---|--|--|
| T _s MAX to T _L (Ramp-up Rate) | 5°C/Second Maximum | |
| Preheat | | |
| - Temperature Minimum (T _s MIN) | N/A | |
| - Temperature Typical (T _s TYP) | 150°C | |
| - Temperature Maximum(T _s MAX) | N/A | |
| - Time (t _s MIN) | 30 - 60 Seconds | |
| Ramp-up Rate (T _L to T _P) | 5°C/Second Maximum | |
| Time Maintained Above: | | |
| - Temperature (T _L) | 150°C | |
| - Time (t _∟) | 200 Seconds Maximum | |
| Peak Temperature (T _P) | 245°C Maximum | |
| Target Peak Temperature(T _P Target) | 245°C Maximum 2 Times/230°C Maximum 1Time | |
| Time within 5°C of actual peak (t _P) | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time | |
| Ramp-down Rate | 5°C/Second Maximum | |
| Time 25°C to Peak Temperature (t) | N/A | |
| Moisture Sensitivity Level | Level 1 | |
| Additional Notes | Temperatures shown are applied to body of device. | |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)